



SPP8637

P-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPP8637 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. The SPP8637 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

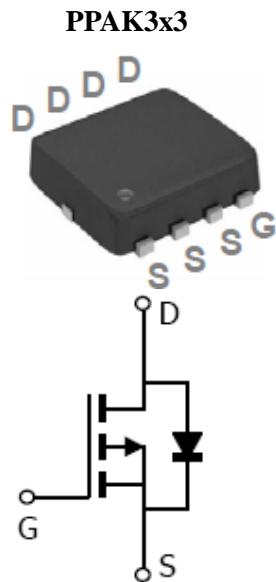
FEATURES

- ◆ -30V/-30A, $R_{DS(ON)}=8.5\text{m}\Omega$ @ $V_{GS}=-10\text{V}$
- ◆ -30V/-20A, $R_{DS(ON)}=14.5\text{m}\Omega$ @ $V_{GS}=-4.5\text{V}$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ PPAK3x3 package design

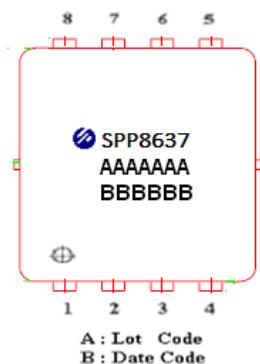
APPLICATIONS

- MB/VGA/Vcore/PD Application
- DC/DC Power System
- Load Switch

PIN CONFIGURATION



PART MARKING



A : Lot Code
B : Date Code
(YY / MM / DD)



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PPAK3x3 PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

ORDERING INFORMATION

Part Number	Package	Part Marking
SPP8637DN8RGB	PPAK3x3	SPP8637

※ SPP8637DN8RGB : Tape Reel ; Pb – Free ; Halogen - Free

ABSOLUTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-30	V
Gate –Source Voltage	V _{GSS}	±20	V
Continuous Drain Current TA=25°C	I _D	-50	A
TA=100°C		-32	
Pulsed Drain Current	I _{DM}	-200	A
Power Dissipation	P _D	59	W
Operating Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient (t≤10s)	R _{θJA}	62	°C/W



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ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, ID=-250uA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , ID=-250uA	-1.0		-2.5	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V			-1	
		V _{DS} =-24V, V _{GS} =0V, T _J =100°C			-10	uA
On-State Drain Current	I _{D(on)}	V _{DS} ≥-5V, V _{GS} =-10V			-100	A
Drain-Source On-Resistance	R _{D(on)}	V _{GS} = -10V, ID=-30A		7	8.5	
		V _{GS} =-4.5V, ID=-20A		11.4	14.5	mΩ
Gate Resistance	R _g	V _{DS} =0V, V _{GS} =0V, f=1MHz		8.5	12	Ω
Forward Transconductance	g _{fs}	V _{DS} =-10V, ID=-3A		14		S
Diode Forward Voltage	V _{SD}	I _S =-1A, V _{GS} =0V			-1	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-15V, V _{GS} =-4.5V ID= -10A		35		nC
Gate-Source Charge	Q _{gs}			11		
Gate-Drain Charge	Q _{gd}			10.5		
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V f=1MHz		3300		pF
Output Capacitance	C _{oss}			410		
Reverse Transfer Capacitance	C _{rss}			280		
Turn-On Time	t _{d(on)}	V _{DD} =-15V, ID=-1A, V _{GS} =-10V, R _G =6Ω		24.5		nS
	t _r			10.5		
Turn-Off Time	t _{d(off)}			156		
	t _f			50		



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TYPICAL CHARACTERISTICS

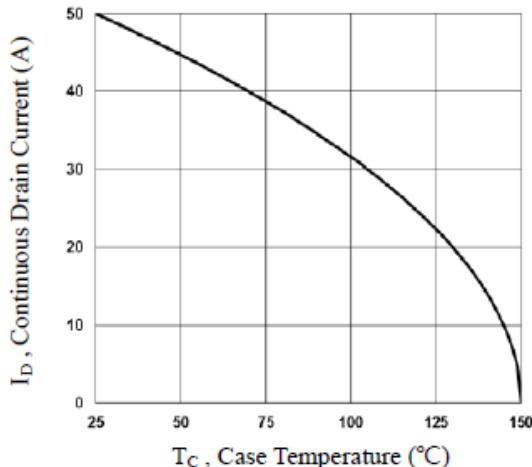


Fig.1 Continuous Drain Current vs. T_c

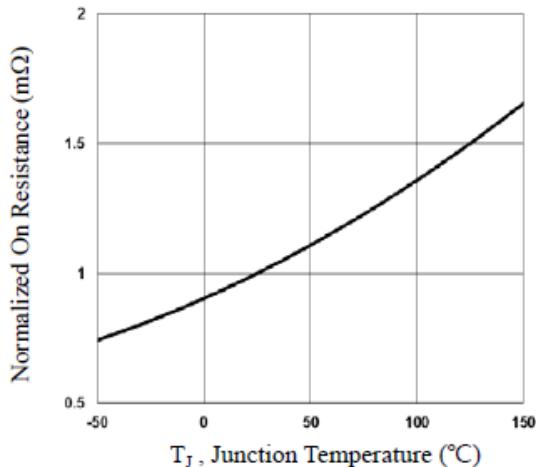


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

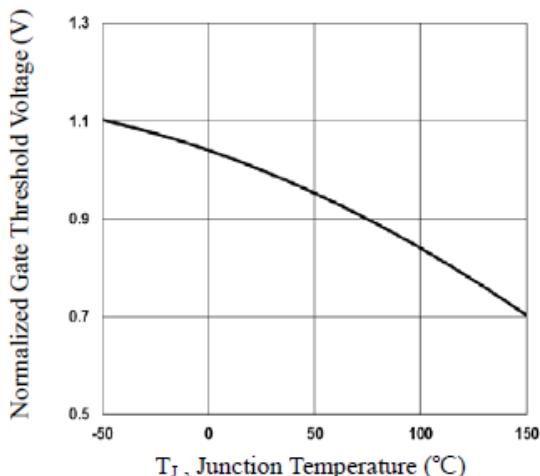


Fig.3 Normalized V_{th} vs. T_j

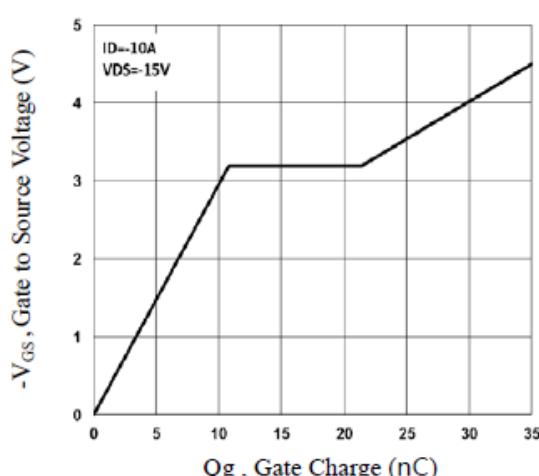


Fig.4 Gate Charge Waveform

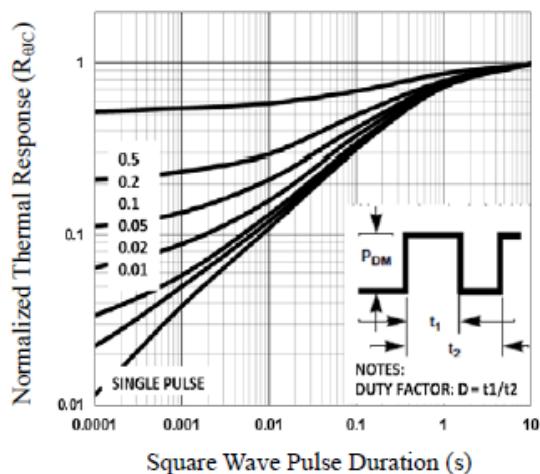


Fig.5 Normalized Transient Impedance

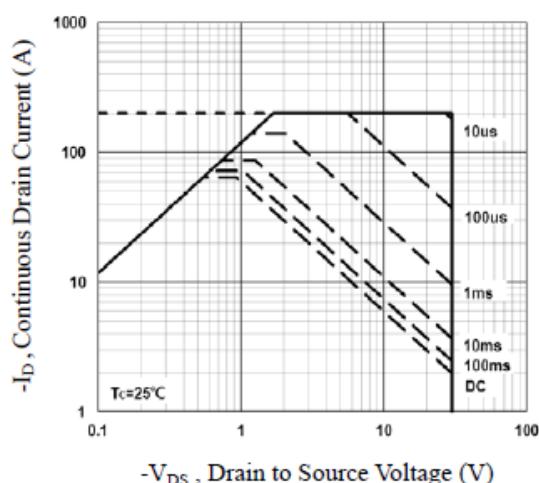


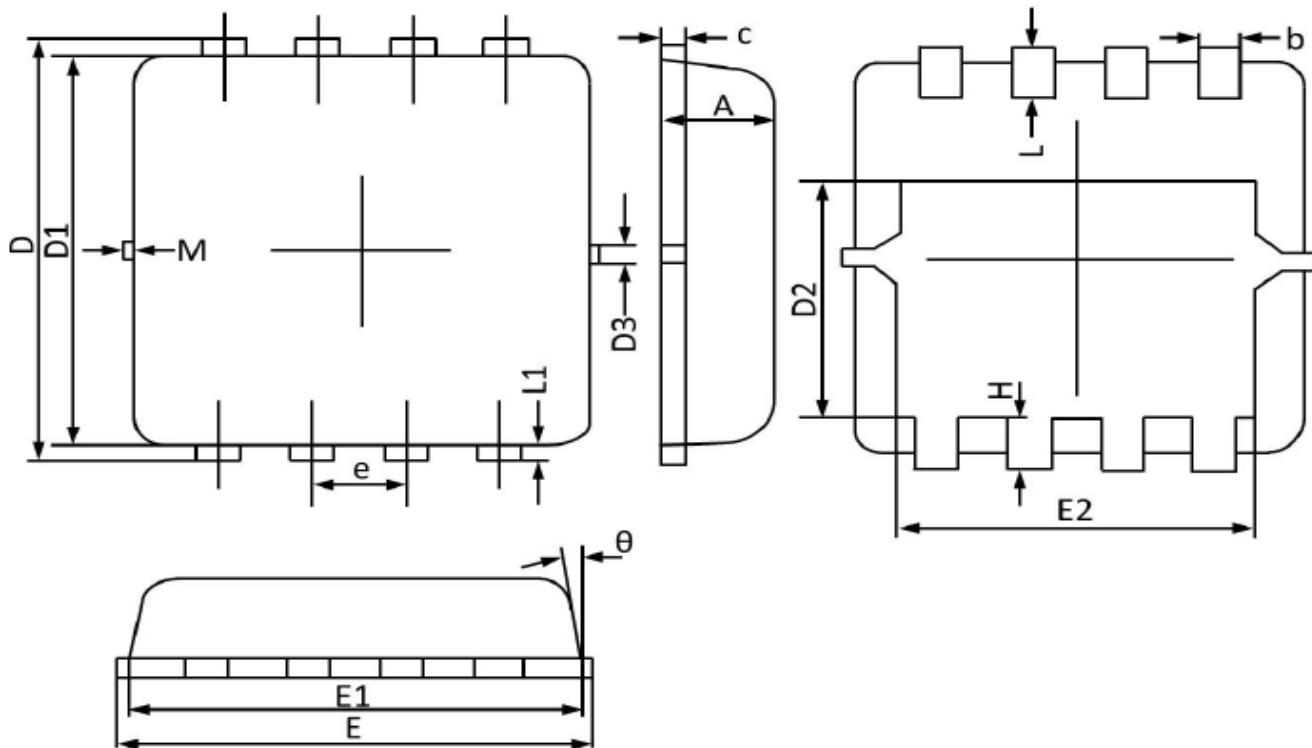
Fig.6 Maximum Safe Operation Area



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PPAK3x3 PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
b	0.250	0.350	0.010	0.013
c	0.100	0.250	0.004	0.009
D	3.250	3.450	0.128	0.135
D1	3.000	3.200	0.119	0.125
D2	1.780	1.980	0.070	0.077
D3	0.130 REF		0.005 REF	
E	3.200	3.400	0.126	0.133
E1	3.000	3.200	0.119	0.125
E2	2.390	2.590	0.094	0.102
e	0.650 BSC		0.026 BSC	
H	0.300	0.500	0.011	0.019
L	0.300	0.500	0.011	0.019
L1	0.130 REF		0.005 REF	
θ	0°	12°	0°	12°
M	0.150 REF		0.006 REF	



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